

WHAT IS CLAIMED IS:

1. An image pickup device including:

a light-transmissible board having a wiring pattern formed on one surface thereof and containing an optical filter; and

an image pickup element having a photodetecting portion formed on the same surface thereof, said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is opposite to an area where there is no wiring-pattern.

2. The image pickup device as claimed in claim 1, wherein said optical filter is an infrared rays cutting filter.

3. The image pickup device as claimed in claim 1, wherein the peripheral edge portion of said image pickup element is sealed with resin.

4. A camera module including:

a light-transmissible board having a wiring pattern formed on one surface thereof and containing an optical filter;

an image pickup element having a photodetecting portion formed on the same surface thereof; and

photodetecting portion of said image pickup element, said image

pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is opposite to an area where there is no wiring-pattern.

5. A camera system using a camera module including:

a light-transmissible board having a wiring pattern formed on one surface thereof and containing an optical filter;

an image pickup element having a photodetecting portion formed on the same surface thereof; and

a lens unit mounted on the other surface of said light-transmissible board so as to be located above said photodetecting portion of said image pickup element, said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is confronted to a wiring-pattern non-forming area.